General Purpose Transistors

PNP Silicon

This transistor is designed for general purpose amplifier applications. It is housed in the SOT-416/SC-75 package which is designed for low power surface mount applications.

Features

- NSVM Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	V _{CEO}	-40	Vdc
Collector-Base Voltage	V _{CBO}	-40	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous	Ic	-200	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, FR-4 Board (Note 1) @T _A = 25°C Derated above 25°C	P _D	200 1.6	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	600	°C/W
Total Device Dissipation, FR-4 Board (Note 2) @T _A = 25°C Derated above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	400	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

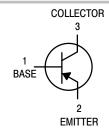
- 1. FR-4 @ Minimum Pad
- 2. FR-4 @ 1.0 × 1.0 Inch Pad



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GENERAL PURPOSE AMPLIFIER TRANSISTORS SURFACE MOUNT





CASE 463 SOT-416/SC-75 STYLE 1

MARKING DIAGRAM



2A = Device Code M = Date Code* • = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping _†
MMBT3906TT1G	SOT-416 (Pb-Free)	3000 / Tape & Reel
NSVMMBT3906TT1G	SOT-416 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

	Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERIST	TICS	<u>.</u>				
	ctor-Emitter Breakdown Voltage (Note 3) c = -1.0 mAdc, I _B = 0)		-40	-	Vdc	
Collector – Base Break ($I_C = -10 \mu Adc$, $I_E = -10 \mu Adc$)	V _(BR) CBO	-40	-	Vdc		
Emitter – Base Breakdo ($I_E = -10 \mu Adc, I_C =$			-5.0	-	Vdc	
Base Cutoff Current (V _{CE} = -30 Vdc, V _E	_{EB} = -3.0 Vdc)	I _{BL}	_	-50	nAdd	
Collector Cutoff Currer (V _{CE} = -30 Vdc, V _E	I _{CEX}	_	-50	nAdd		
ON CHARACTERISTI	CS (Note 3)	•	•	•	•	
DC Current Gain	_{CE} = -1.0 Vdc) _{DE} = -1.0 Vdc) _{DE} = -1.0 Vdc)	h _{FE}	60 80 100 60 30	- 300 - -	_	
Collector – Emitter Satu ($I_C = -10 \text{ mAdc}, I_B$ ($I_C = -50 \text{ mAdc}, I_B$	= -1.0 mAdc)	V _{CE(sat)}	_ _	-0.25 -0.4	Vdc	
Base – Emitter Saturati ($I_C = -10$ mAdc, I_B ($I_C = -50$ mAdc, I_B	= -1.0 mAdc)	V _{BE(sat)}	-0.65 -	-0.85 -0.95	Vdc	
SMALL-SIGNAL CHA	ARACTERISTICS					
Current-Gain - Bandy (I _C = -10 mAdc, V _C	width Product _{CE} = −20 Vdc, f = 100 MHz)	f _⊤	250	_	MHz	
Output Capacitance (V _{CB} = -5.0 Vdc, I _E	= 0, f = 1.0 MHz)	C _{obo}	-	4.5	pF	
Input Capacitance1 (V _{EB} = -0.5 Vdc, I _C	c = 0, f = 1.0 MHz)	C _{ibo}	_	10.0	pF	
Input Impedance (V _{CE} = -10 Vdc, I _C	= -1.0 mAdc, f = 1.0 kHz)	h _{ie}	2.0	12	kΩ	
Voltage Feedback Rat (V _{CE} = -10 Vdc, I _C	io = -1.0 mAdc, f = 1.0 kHz)	h _{re}	0.1	10	X 10 ⁻	
Small – Signal Current Gain (V _{CE} = -10 Vdc, I _C = -1.0 mAdc, f = 1.0 kHz)		h _{fe}	100	400	-	
Output Admittance (V _{CE} = -10 Vdc, I _C	h _{oe}	3.0	60	μmho		
Noise Figure (V _{CE} = -5.0 Vdc, I _C	$_{\rm S}$ = -100 μAdc, R _S = 1.0 k Ω, f = 1.0 kHz)	NF	-	4.0	dB	
SWITCHING CHARAC	CTERISTICS					
Delay Time	$(V_{CC} = -3.0 \text{ Vdc}, V_{BE} = 0.5 \text{ Vdc})$	t _d	_	35		
Rise Time	$(I_C = -10 \text{ mAdc}, I_{B1} = -1.0 \text{ mAdc})$	t _r	-	35	ns	
Storage Time $(V_{CC} = -3.0 \text{ Vdc}, I_C = -10 \text{ mAdc})$		t _s	_	225	ns	
Fall Time	$(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$	t _f	_	75		

^{3.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

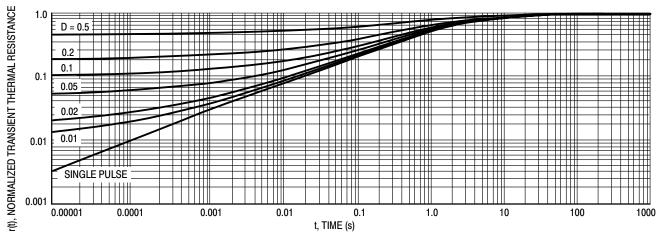
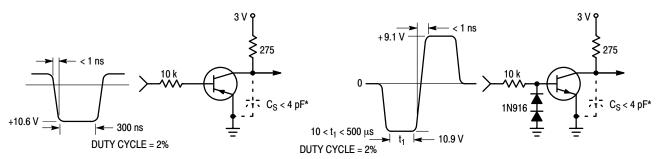


Figure 1. Normalized Thermal Response



* Total shunt capacitance of test jig and connectors

Figure 2. Delay and Rise Time Equivalent Test Circuit

Figure 3. Storage and Fall Time Equivalent Test Circuit

TYPICAL TRANSIENT CHARACTERISTICS

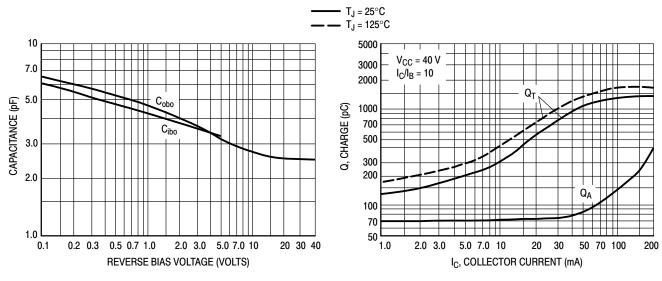


Figure 4. Capacitance

Figure 5. Charge Data

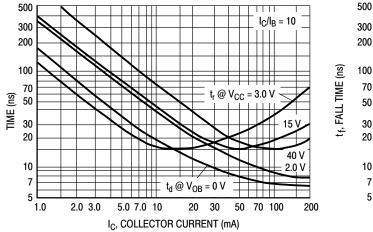


Figure 6. Turn-On Time

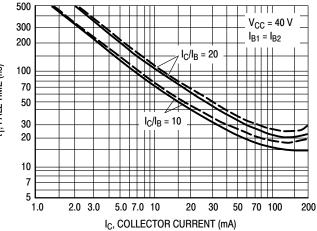
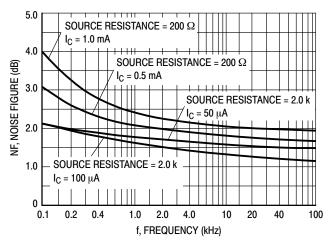


Figure 7. Fall Time

TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

 $(V_{CE} = -5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, Bandwidth = 1.0 \text{ Hz})$



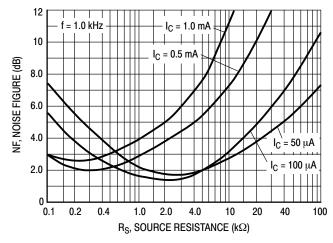
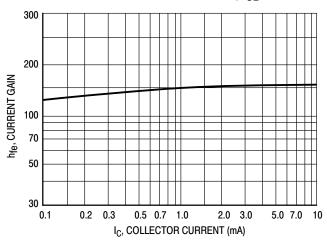


Figure 8.

Figure 9.

h PARAMETERS

 $(V_{CE} = -10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C})$



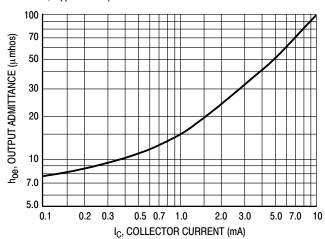


Figure 10. Current Gain

20 10 7.0 h_{ie} , INPUT IMPEDANCE ($k\Omega$) 5.0 3.0 2.0 1.0 0.7 0.5 0.3 0.2 0.1 0.2 0.5 0.7 1.0 5.0 7.0 IC, COLLECTOR CURRENT (mA)

Figure 11. Output Admittance

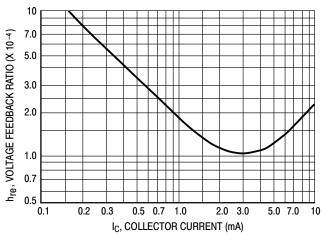


Figure 12. Input Impedance

Figure 13. Voltage Feedback Ratio

STATIC CHARACTERISTICS

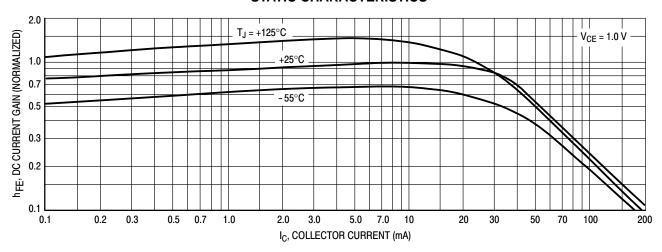


Figure 14. DC Current Gain

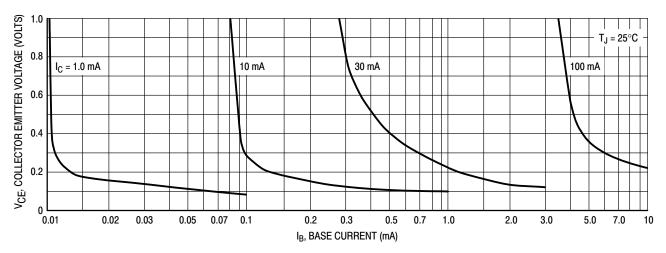


Figure 15. Collector Saturation Region

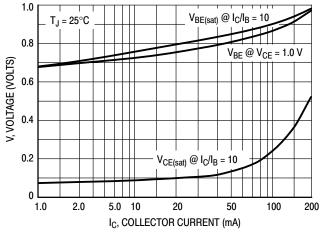


Figure 16. "ON" Voltages

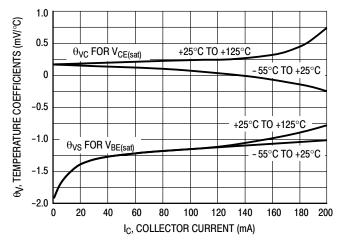
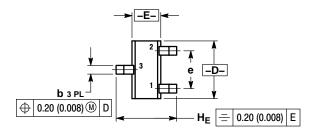


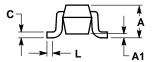
Figure 17. Temperature Coefficients

PACKAGE DIMENSIONS

SC-75/SOT-416

CASE 463 ISSUE G





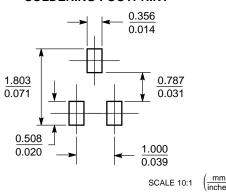
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.70	0.80	0.90	0.027	0.031	0.035
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.15	0.20	0.30	0.006	0.008	0.012
С	0.10	0.15	0.25	0.004	0.006	0.010
D	1.55	1.60	1.65	0.061	0.063	0.065
Е	E 0.70 0.80		0.90	0.027	0.031	0.035
е	1.00 BSC			(0.04 BSC	
L	0.10	0.15	0.20	0.004	0.006	0.008
HE	1.50	1.60	1.70	0.060	0.063	0.067

STYLE 1: PIN 1. BASE 2. EMITTER 3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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